

Customer Information Notification Update

202202017 IU01: Visual Cosmetic Change to Product Appearance for Various ATKH QFP Packages

Note: This notice is NXP Company Proprietary.

Issue Date: Aug 11, 2022 Effective date: Aug 12, 2022

Here is your personalized notification about a NXP general announcement.

For detailed information we invite you to view this notification online

Management summary

Visual Cosmetic Change to Product Appearance for Various ATKH QFP Packages

Change Category

[]Wafer Fab Process	[]Assembly Process	[]Product Marking	[]Test Process	[]Design
[]Wafer Fab Materials	[]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
[]Wafer Fab Location	[]Assembly Location	[]Packing/Shipping/Labeling	[]Test Location	[]Electrical spec./Test coverage
[]Firmware	[X]Other: Change of visual cosmetic appearance of			

[]Firmware

product package

PCN Overview

Description

Our Assembly Site ATKH in Kaohsiung Taiwan is upgrading moulding equipment, which will result in visual cosmetic changes to product appearance for various QFP packages.

Reason

For affected products our Manufacturing Site in Taiwan is upgrading their moulding equipment.

Identification of Affected Products

Changed products can be identified by the added ejector marks and the date code in the final line(s) of the product's top marking. This date code is also shown on packing labelling.

Change over planning is indicated in the type list in the excel file attached to this mail notification

For example change over in wk2212 (wk 12 of 2022) means:

- · Products with datecodes up to and including wk2211 will be produced on old equipment
- Products with datecodes wk2212 and later will be produced on new equipment

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Disposition of Old Products

Existing inventory will be shipped until depleted

Remarks

Please use the link 'view online' under the heading 'Additional information' above, to log in to the NXP e-PCN system you're subscribed to, in order to obtain the attached document 'Attachment to NXP CIN 202202017I.pdf' with relevant detailed information from the tab 'Files'.

Should you not be able to obtain this document, please contact your NXP sales representative or the e-mail address mentioned below under 'Contact and Support'.

Update Information

Most of the changes communicated via CIN202202017 have already been implemented, but this updated CIN communicates that part of conversion has been cancelled.

For the products in TQFP64, LQFP64, LQFP32 and part of products in HTQFP64 the change will not be introduced. Please see the attached excel file that describes the status update for each Sales Item.

The reason for this update is that due changes to internal loading, part of the program has been cancelled.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply .

NXP Semiconductors

High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006- 2022 NXP Semiconductors. All rights reserved.

	Affected
Affected Part Number	12NC
LPC845M301JBD64E	935336506551
LPC11E67JBD64E	935304417551
PCA8537BH/Q900/1,5	935297896518
PCA8547BHT/AY	935303764518
PCF8537BH/1,518	935297898518
TDA8020HL/C2,118	935272983118
LPC12H27FBD64/301,	935296515151
PCF8576CHL/1,118	935290305118
LPC54101J256BD64QL	935305132151
LPC54101J512BD64QL	935305134151
LPC54102J256BD64QL	935305136151
LPC54102J512BD64QL	935305138151
LPC54114J256BD64QL	935306186151

LPC865M201JBD64E	935427812551
LPC864M201JBD64E	935427813551
LPC51U68JBD64EL	935361248157
LPC11U67JBD64E	935304418551
LPC2134FBD64/01,11	935281774118
LPC1227FBD64/301,1	935293249151
LPC1224FBD64/101,1	935294968151
LPC11U68JBD64Y	935302501518
LPC2131FBD64/01,11	935281771118
LPC2131FBD64/01,15	935281771151
LPC2132FBD64/01,11	935281772118
LPC2136FBD64/01EL	935281775157
LPC2138FBD64/01,11	935281776118
LPC2138FBD64/01,15	935281776151
LPC2138FBD64/01EL	935281776157
LPC1226FBD64/301,1	935293251151
LPC1224FBD64/121,1	935294971151
LPC11E68JBD64K	935302488557
LPC11E36FBD64/501E	935299678551
LPC11E37FBD64/501E	935299679551
LPC11U37HFBD64/4QL	935303305151
LPC11E37HFBD64/4QL	935303306151
LPC1225FBD64/301,1	935293582151
LPC1225FBD64/321,1	935293587151
LPC2132FBD64/01EL	935281772157
LPC2134FBD64/01EL	935281774157
LPC11U68JBD64E	935302501551
LPC844M201JBD64E	935336502551
LPC12H25FBD64/301,	935296514151
LPC51U68JBD64QL	935361248151
PCF8578HT/1,518	935289189518
PCF85176H/1,518	935290063518
PCA85176H/Q900/1,5	935290065518
PCA8537AH/Q900/1,5	935297895518
PCF8537AH/1,518	935297897518
LPC54113J256BD64QL	935308457151
PCA8547AHT/AY	935303763518
PCF8579HT/1	935289191518
LPC54113J128BD64QL	935308456151
LPC2132FBD64/01,15	935281772151
LPC2134FBD64/01,15	935281774151
LPC2136FBD64/01,15	935281775151
LPC11E68JBD64E	935302488551
LPC11U68JBD64K	935302501557